The SN54165 and SN74165 devices are obsolete and are no longer supplied.

SDLS062D – OCTOBER 1976 – REVISED FEBRUARY 2002

- **Complementary Outputs**
- **Direct Overriding Load (Data) Inputs**
- **Gated Clock Inputs**
- **Parallel-to-Serial Data Conversion**

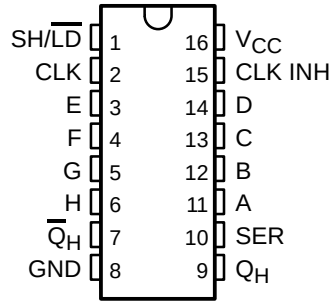
TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY	TYPICAL POWER DISSIPATION
’165	26 MHz	210 mW
’LS165A	35 MHz	90 mW

description

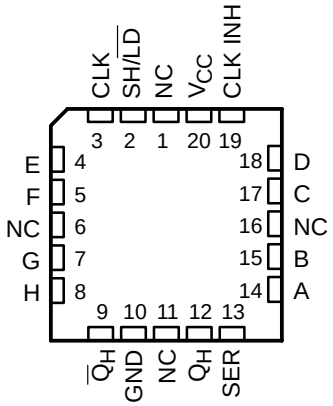
The ’165 and ’LS165A are 8-bit serial shift registers that shift the data in the direction of Q_A toward Q_H when clocked. Parallel-in access to each stage is made available by eight individual, direct data inputs that are enabled by a low level at the shift/load (SH/$\overline{LD}$) input. These registers also feature gated clock (CLK) inputs and complementary outputs from the eighth bit. All inputs are diode-clamped to minimize transmission-line effects, thereby simplifying system design.

Clocking is accomplished through a two-input positive-NOR gate, permitting one input to be used as a clock-inhibit function. Holding either of the clock inputs high inhibits clocking, and holding either clock input low with SH/$\overline{LD}$ high enables the other clock input. Clock inhibit (CLK INH) should be changed to the high level only while CLK is high. Parallel loading is inhibited as long as SH/$\overline{LD}$ is high. Data at the parallel inputs are loaded directly into the register while SH/$\overline{LD}$ is low, independently of the levels of CLK, CLK INH, or serial (SER) inputs.

SN54165, SN54LS165A . . . J OR W PACKAGE
SN74165 . . . N PACKAGE
SN74LS165A . . . D, N, OR NS PACKAGE
(TOP VIEW)



SN54LS165A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 2002, Texas Instruments Incorporated

On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

The SN54165 and SN74165 devices are obsolete and are no longer supplied.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74LS165AN	SN74LS165AN
	SOIC – D	Tube	SN74LS165AD	LS165A
		Tape and reel	SN74LS165ADR	
	SOP – NS	Tape and reel	SN74LS165ANSR	74LS165A
–55°C to 125°C	CDIP – J	Tube	SN54LS165AJ	SN54LS165AJ
		Tube	SNJ54LS165AJ	SNJ54LS165AJ
	CFP – W	Tube	SNJ54LS165AW	SNJ54LS165AW
	LCCC – FK	Tube	SNJ54LS165AFK	SNJ54LS165AFK

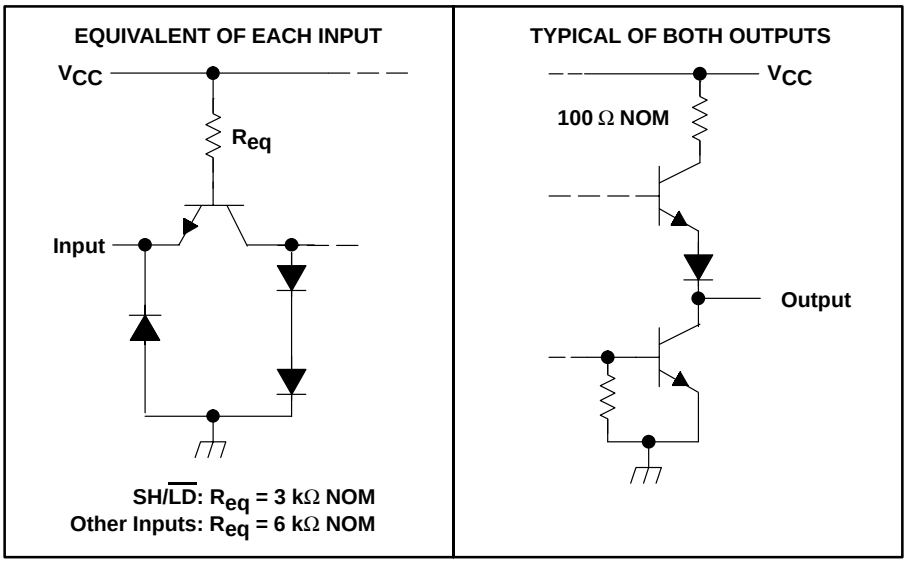
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

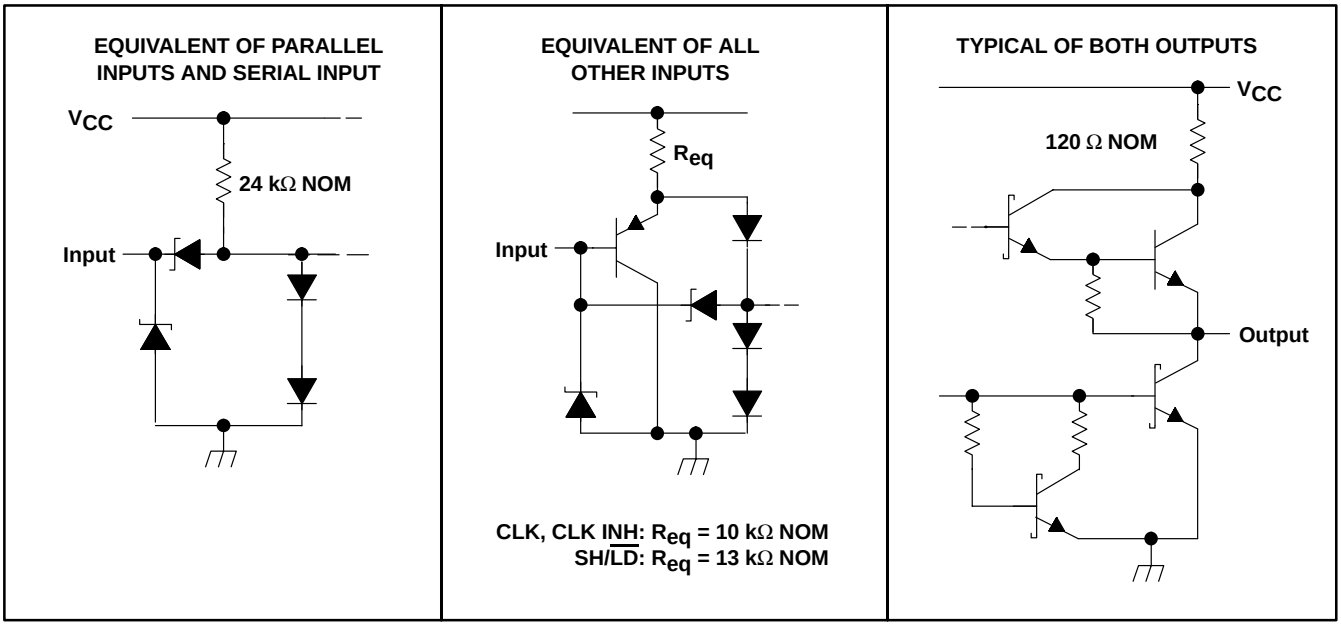
INPUTS					INTERNAL OUTPUTS		OUTPUT Q_H
SH/$\overline{LD}$	CLK INH	CLK	SER	PARALLEL A . . . H	$\overline{Q}_A$	$\overline{Q}_B$	
L	X	X	X	a . . . h	a	b	h
H	L	L	X	X	Q_{A0}	Q_{B0}	Q_{H0}
H	L	↑	H	X	H	Q_{An}	Q_{Gn}
H	L	↑	L	X	L	Q_{An}	Q_{Gn}
H	H	X	X	X	Q_{A0}	Q_{B0}	Q_{H0}

schematics of inputs and outputs

'165

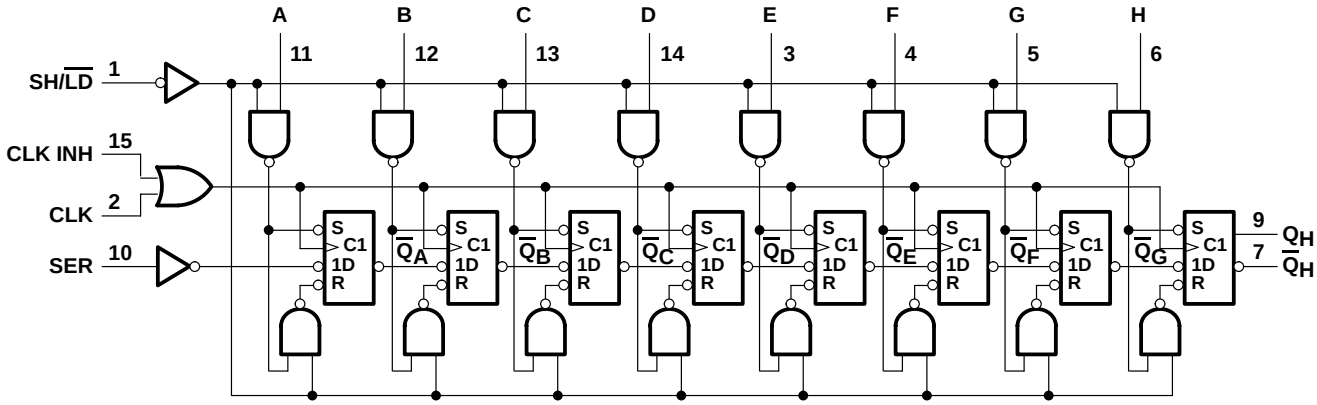


'LS165A



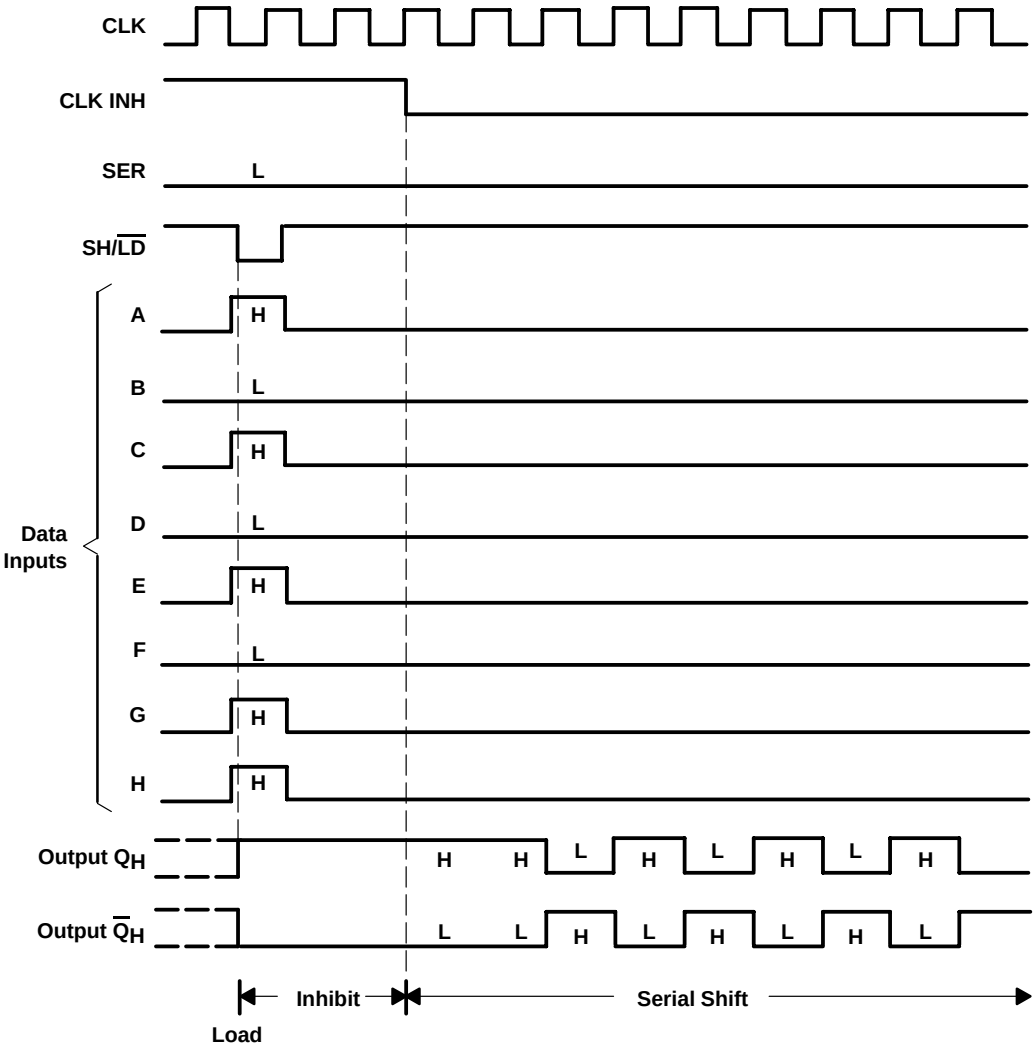
The SN54165 and SN74165 devices are obsolete and are no longer supplied.

logic diagram (positive logic)



Pin numbers shown are for D, J, N, NS, and W packages.

typical shift, load, and inhibit sequences



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage, V_I: SN54165, SN74165 . . . . . 5.5 V
SN54LS165A, SN74LS165A . . . . . 7 V
Interemitter voltage (see Note 2) . . . . . 5.5 V
Package thermal impedance θ_{JA} (see Note 3): D package . . . . . 73°C/W
N package . . . . . 67°C/W
NS package . . . . . 64°C/W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Voltage values, except interemitter voltage, are with respect to network ground terminal.
2. This is the voltage between two emitters of a multiple-emitter transistor. This rating applies for the '165 to the SH/$\overline{LD}$ input in conjunction with the CLK INH input.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		SN54165			SN74165			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
I_{OH}	High-level output current			–800			–800	μA
I_{OL}	Low-level output current			16			16	mA
f_{clock}	Clock frequency	0		20	0		20	MHz
$t_{w(clock)}$	Width of clock input pulse	25			25			ns
$t_{w(load)}$	Width of load input pulse	15			15			ns
t_{su}	Clock-enable setup time (see Figure 1)	30			30			ns
t_{su}	Parallel input setup time (see Figure 1)	10			10			ns
t_{su}	Serial input setup time (see Figure 1)	20			20			ns
t_{su}	Shift setup time (see Figure 1)	45			45			ns
t_h	Hold time at any input	0			0			ns
T_A	Operating free-air temperature	–55		125	0		70	°C

The SN54165 and SN74165 devices are obsolete and are no longer supplied.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†	SN54165			SN74165			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage			2			2			V
V_{IL}	Low-level input voltage					0.8			0.8	V
V_{IK}	Input clamp voltage		V_{CC} = MIN, I_I = –12 mA			–1.5			–1.5	V
V_{OH}	High-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = –800 μA	2.4	3.4		2.4	3.4		V
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I_I	Input current at maximum input voltage		V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	High-level input current	SH/$\overline{LD}$	V_{CC} = MAX, V_I = 2.4 V			80			80	μA
		Other inputs				40			40	
I_{IL}	Low-level input current	SH/$\overline{LD}$	V_{CC} = MAX, V_I = 0.4 V			–3.2			–3.2	mA
		Other inputs				–1.6			–1.6	
I_{OS}	Short-circuit output current§		V_{CC} = MAX	–20		–55	–18		–55	mA
I_{CC}	Supply current		V_{CC} = MAX, See Note 4		42	63		42	63	mA

NOTE 4: With the outputs open, CLK INH and CLK at 4.5 V, and a clock pulse applied to SH/$\overline{LD}$, I_{CC} is measured first with the parallel inputs at 4.5 V, then with the parallel inputs grounded.

† For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time.

SN54165 and SN74165 switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}				20	26		MHz
t_{PLH}	$\overline{LD}$	Any	C_L = 15 pF, R_L = 400 Ω		21	31	ns
t_{PHL}					27	40	
t_{PLH}	CLK	Any	C_L = 15 pF, R_L = 400 Ω		16	24	ns
t_{PHL}					21	31	
t_{PLH}	H	Q_H	C_L = 15 pF, R_L = 400 Ω		11	17	ns
t_{PHL}					24	36	
t_{PLH}	H	$\overline{Q}_H$	C_L = 15 pF, R_L = 400 Ω		18	27	ns
t_{PHL}					18	27	

¶ f_{max} = maximum clock frequency, t_{PLH} = propagation delay time, low-to-high-level output, t_{PHL} = propagation delay time, high-to-low-level output

The SN54165 and SN74165 devices are obsolete and are no longer supplied.

recommended operating conditions

			SN54LS165A			SN74LS165A			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.7			0.8	V
I_{OH}	High-level output current				–0.4			–0.4	mA
I_{OL}	Low-level output current				4			8	mA
f_{clock}	Clock frequency		0		25	0		25	MHz
$t_{w(clock)}$	Width of clock input pulse (see Figure 2)	Clock high	15			15			ns
		Clock low	25			25			
$t_{w(load)}$	Width of load input pulse	Clock high	25			25			ns
		Clock low	17			17			
t_{su}	Clock-enable setup time (see Figure 2)		30			30			ns
t_{su}	Parallel input setup time (see Figure 2)		10			10			ns
t_{su}	Serial input setup time (see Figure 2)		20			20			ns
t_{su}	Shift setup time (see Figure 2)		45			45			ns
t_h	Hold time at any input		0			0			ns
T_A	Operating free-air temperature		–55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†			SN54LS165A			SN74LS165A			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = –18 mA					–1.5			–1.5	V
V_{OH}	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX,		I_{OH} = –0.4 mA	2.5	3.5		2.7	3.5		V
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX		I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
			I_{OL} = 8 mA					0.35	0.5	
I_I	V_{CC} = MAX, V_I = 7 V					0.1			0.1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.7 V					20			20	μA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V					–0.4			–0.4	mA
I_{OS}§	V_{CC} = MAX			–20		–100	–20		–100	mA
I_{CC}	V_{CC} = MAX, See Note 4				18	30		18	30	mA

NOTE 4. With the outputs open, CLK INH and CLK at 4.5 V, and a clock pulse applied to SH/$\overline{LD}$, I_{CC} is measured first with the parallel inputs at 4.5 V, then with the parallel inputs grounded.

† For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

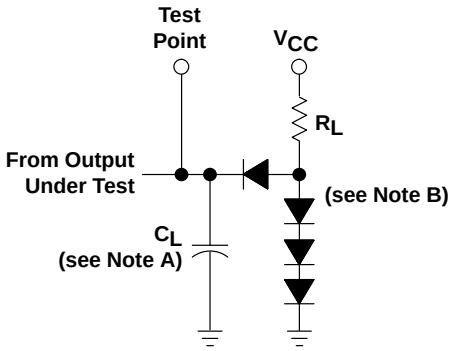
§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

SN54LS165A and SN74LS165A switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 2)

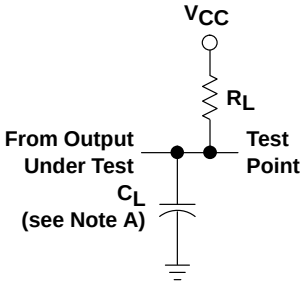
PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}				25	35		MHz
t_{PLH}	$\overline{LD}$	Any	R_L = 2 kΩ, C_L = 15 pF		21	35	ns
t_{PHL}					26	35	
t_{PLH}	CLK	Any	R_L = 2 kΩ, C_L = 15 pF		14	25	ns
t_{PHL}					16	25	
t_{PLH}	H	Q_H	R_L = 2 kΩ, C_L = 15 pF		13	25	ns
t_{PHL}					24	30	
t_{PLH}	H	$\overline{Q}_H$	R_L = 2 kΩ, C_L = 15 pF		19	30	ns
t_{PHL}					17	25	

† f_{max} = maximum clock frequency, t_{PLH} = propagation delay time, low-to-high-level output, t_{PHL} = propagation delay time, high-to-low-level output

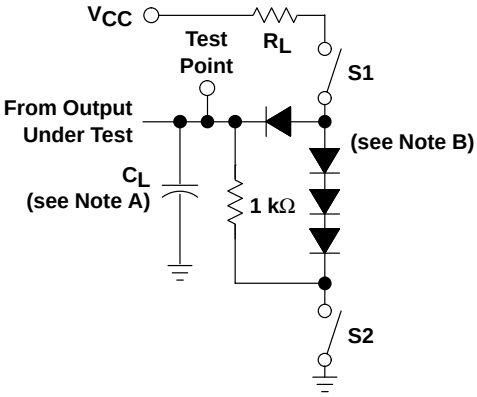
PARAMETER MEASUREMENT INFORMATION
SERIES 54/74 DEVICES



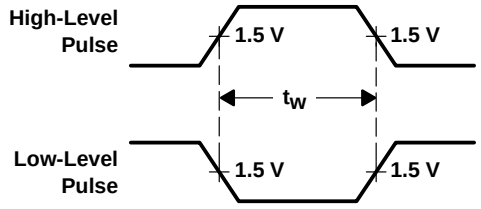
LOAD CIRCUIT FOR 2-STATE TOTEM-POLE OUTPUTS



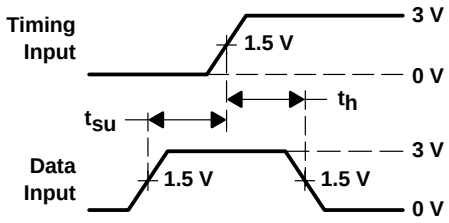
LOAD CIRCUIT FOR OPEN-COLLECTOR OUTPUTS



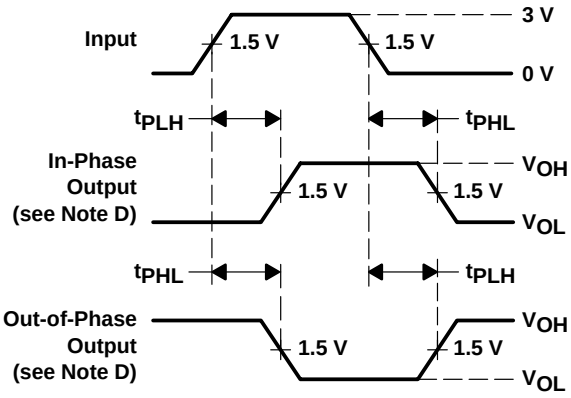
LOAD CIRCUIT FOR 3-STATE OUTPUTS



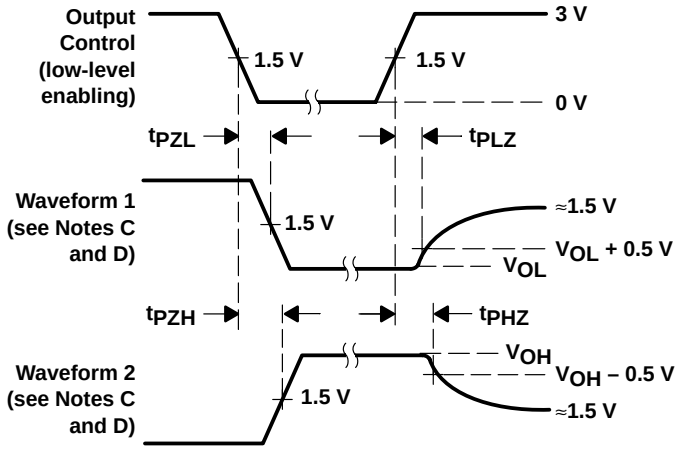
VOLTAGE WAVEFORMS PULSE DURATIONS



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES

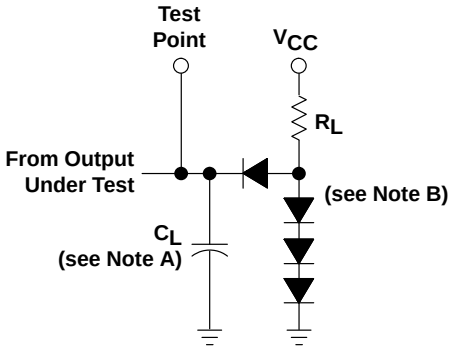


VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

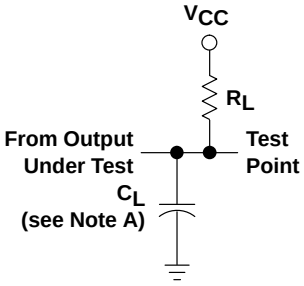
NOTES: A. C_L includes probe and jig capacitance.
B. All diodes are 1N3064 or equivalent.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. S1 and S2 are closed for t_{PLH}, t_{PHL}, t_{PHZ}, and t_{PLZ}; S1 is open and S2 is closed for t_{PZH}; S1 is closed and S2 is open for t_{PZL}.
E. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O \approx 50\ \Omega$; t_r and $t_f \leq 7$ ns for Series 54/74 devices and t_r and $t_f \leq 2.5$ ns for Series 54S/74S devices.
F. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

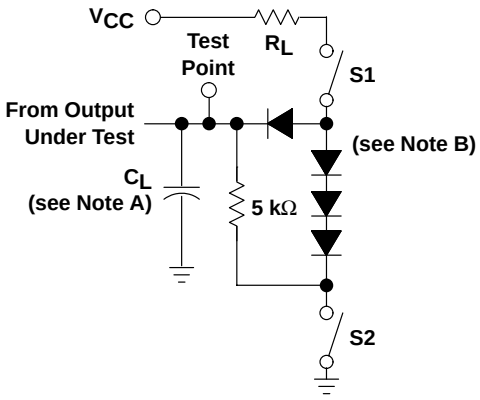
PARAMETER MEASUREMENT INFORMATION
SERIES 54LS/74LS DEVICES



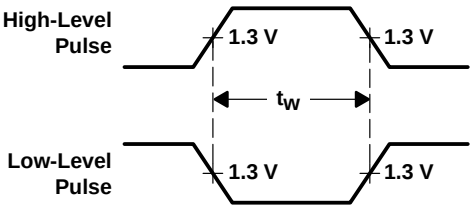
LOAD CIRCUIT FOR 2-STATE TOTEM-POLE OUTPUTS



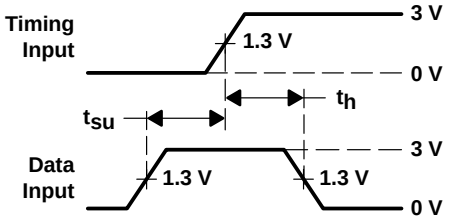
LOAD CIRCUIT FOR OPEN-COLLECTOR OUTPUTS



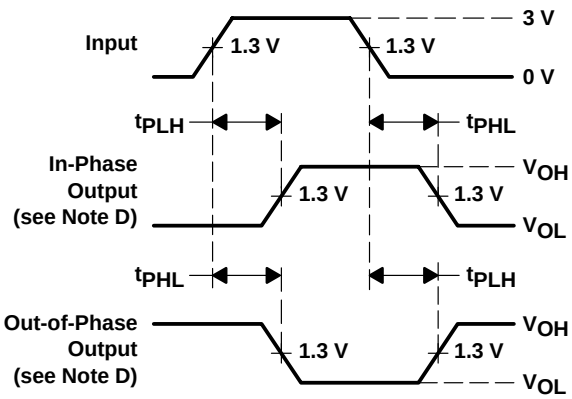
LOAD CIRCUIT FOR 3-STATE OUTPUTS



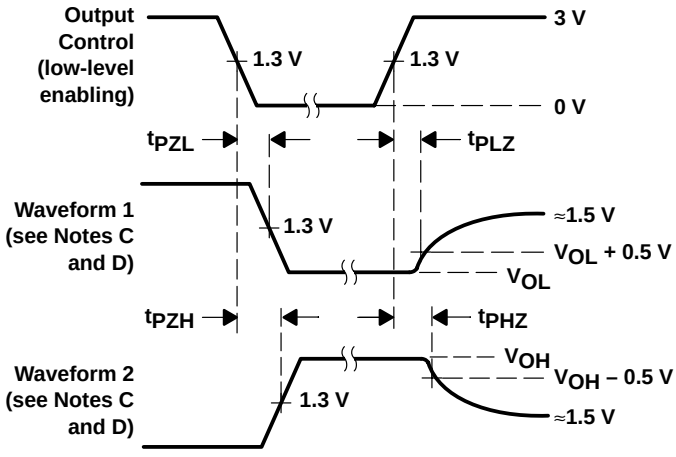
VOLTAGE WAVEFORMS PULSE DURATIONS



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. C_L includes probe and jig capacitance.
B. All diodes are 1N3064 or equivalent.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. S1 and S2 are closed for t_{PLH}, t_{PHL}, t_{PHZ}, and t_{PLZ}; S1 is open and S2 is closed for t_{PZH}; S1 is closed and S2 is open for t_{PZL}.
E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
F. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O \approx 50\ \Omega$, $t_r \le 1.5$ ns, $t_f \le 2.6$ ns.
G. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
5962-7700601VEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	
5962-7700601VFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	
7700601EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
7700601FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
JM38510/30608B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30608BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30608BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
M38510/30608B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/30608BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/30608BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SN54LS165AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN74165N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS165AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS165ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS165ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS165ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS165ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS165ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS165AJ	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
SN74LS165AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS165AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS165ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS165ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS165ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
SNJ54LS165AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS165AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS165AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS165A, SN54LS165A-SP, SN74LS165A :

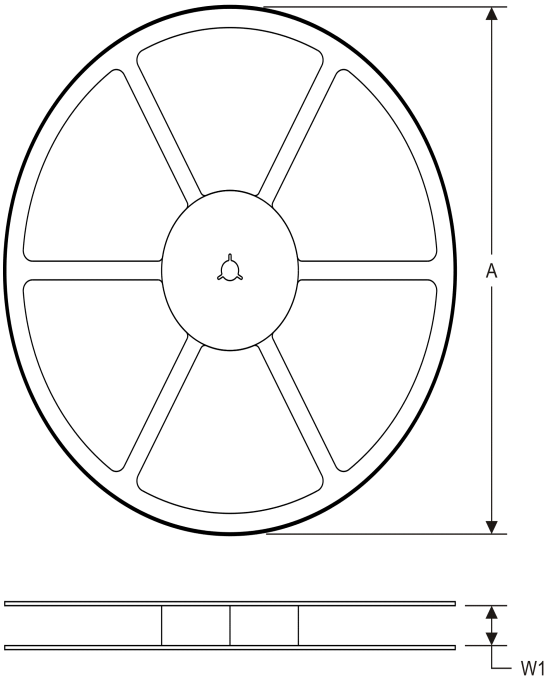
- Catalog: SN74LS165A, SN54LS165A
- Military: SN54LS165A
- Space: SN54LS165A-SP

NOTE: Qualified Version Definitions:

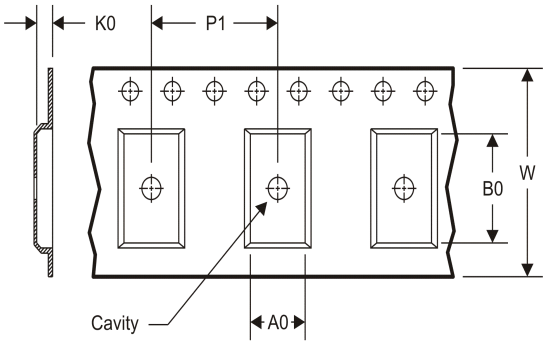
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



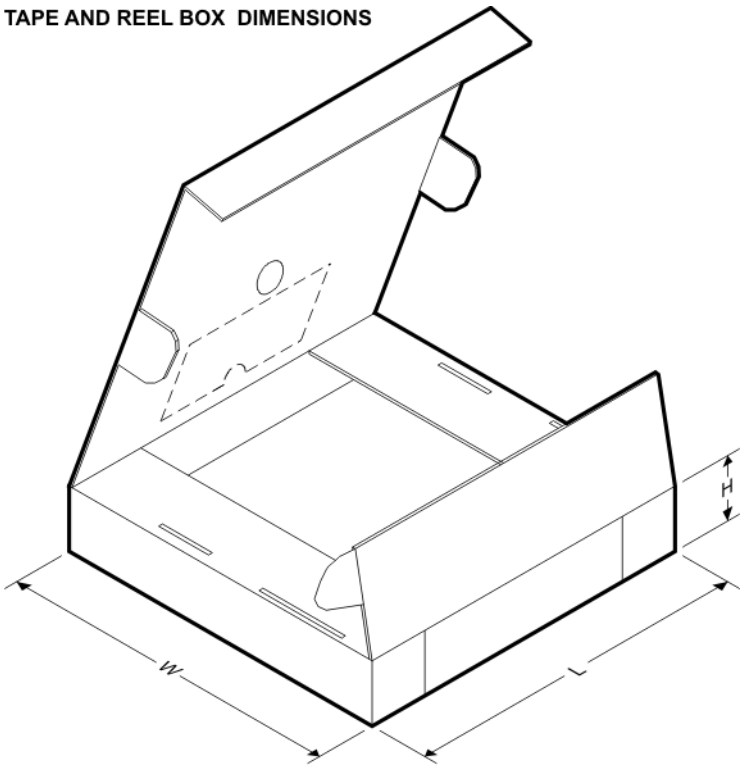
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS165ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS165ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS165ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS165ANSR	SO	NS	16	2000	367.0	367.0	38.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Mobile Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2012, Texas Instruments Incorporated